

# Procedure file

Basic information			
DEA - Delegated acts procedure	<a href="#">2018/2947(DEA)</a>	Procedure completed - delegated act enters into force	
Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages			
Supplementing <a href="#">2008/0240(COD)</a>			
Subject			
3.40.06 Electronics, electrotechnical industries, ICT, robotics			
3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)			
Key players			
European Parliament	Committee responsible	Rapporteur	Appointed
	<b>ENVI</b> Environment, Public Health and Food Safety		